



PK407 (v1.1) April 9, 2012

100% Material Declaration Data Sheet CSG225 for Spartan®-6 FPGAs

Average Weight: 0.3830 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.012563	3.280
	Silicon	7440-21-3	100.00		0.012563	
Die Attach Material					0.002453	0.640
	Silver	7440-22-4	77.50		0.001901	
	Bismaleimide monomer	Trade Secret	15.00		0.000368	
	Acrylate monomer	Trade Secret	7.50		0.000184	
Mold Compound					0.169140	44.162
	Solid Epoxy Resin	Trade Secret	11.00		0.018605	
	Phenol Resin	Trade Secret	11.00		0.018605	
	Fused Silica	60676-86-0	62.40		0.105543	
	Metal Hydroxide	Trade Secret	15.05		0.025456	
	Carbon Black	1333-86-4	0.55		0.000930	
Gold Wire					0.002453	0.640
	Gold	7440-57-5	99.05		0.002430	
	Palladium	7440-05-3	0.95		0.000023	
	Calcium	7440-70-2	0.00		0.000000	
Solder Balls					0.063453	16.567
	Tin	7440-31-5	96.50		0.061232	
	Silver	7440-22-4	3.00		0.001904	
	Copper	7440-50-8	0.50		0.000317	

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Substrate					0.132938	34.710
	Copper	7440-50-8	9.99		0.013281	
	Nickel	7440-02-0	3.52		0.004679	
	Gold	7440-57-5	4.21		0.005597	
	Glass fiber (GF)	65997-17-3	14.92		0.019834	
	Non-halogen flame retardant	1675-54-3	0.06		0.000080	
	BT (core)	105391-33-1 25722-66-1 9003-36-5 21645-51-2 7440-38-2	42.41		0.056379	
	Solder mask	13676-54-5 25722-66-1 147-14-8 7727-43-7 61790-53-2 14807-96-6 461-58-5 7723-14-0	24.89		0.033088	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/31/10	1.0	Initial Xilinx release.
04/09/12	1.1	Component Weight update.

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